

Thermal RC network (Foster)

SPICE thermal model

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
th(j-mb)	thermal resistance from junction to mounting base		-	-	1.89	K/W
	Cth ₁	2.419E-05 F		Ą	t .	
	Cth ₂	2.167E-04 F		_	tj	
	Cth ₃	3.323E-04 F			_	
	Cth ₄	2.213E-03 F			Rth1 Cth	1
	Cth ₅	3.420E-03 F		L L		1
	Cth ₆	6.196E-03 F				
	Cth ₇	2.541E-02 F		Г	5	
	Cth ₈	4.000E+01 F			$\operatorname{Rth}_2 = \operatorname{Cth}_2$	2
	Rth₁	2.335E-03 Ω				
	Rth ₂	4.887E-03 Ω		Г	5 7	
	Rth ₃	2.084E-02 Ω			Rth3 + Cth;	3
	Rth ₄	4.805E-02 Ω			┎╧╺╋╾╌┨	
	Rth ₅	3.344E-01 Ω			_	
	Rth ₆	1.432E+00 Ω				4
	Rth ₇	3.993E-02 Ω		L I		+
	Rth ₈	7.333Ε-03 Ω	(Р		
						5
						6
					Rth7 $=$ Cth	7
Part:	BUK9M23-80E					
ate:	9/5/2016					8
lodel Rth	1.89 K/W					
					t _{amb}	
				v	001aal76	8

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